

PCN Number:	20190107004.0	PCN Date:	January 23, 2019
Title:	Datasheet for TMP112-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TMP112-Q1

SLOS887E – SEPTEMBER 2014 – REVISED DECEMBER 2018

Changes from Revision D (December 2015) to Revision E	Page
• Updated description for ADD0 pin for connection to SDA and SCL	4
• Changed supply voltage maximum value from: 5 V to: 4 V	4
• Changed input voltage maximum value for the SCL, ADD0, and SDA pins from: 5 V to: 4 V	4
• Changed input voltage maximum value for the ALERT pin from: (V+) + 0.5 V to: (V+) + 0.3 and ≤ 4	4
• Updated junction-to-ambient thermal resistance from 200 °C/W to 210.3 °C/W	5
• Updated junction-to-case (top) thermal resistance from 73.7 °C/W to 105.0 °C/W	5
• Updated junction-to-board thermal resistance from 34.4 °C/W to 87.5 °C/W	5
• Updated junction-to-top characterization parameter from 3.1 °C/W to 6.1 °C/W	5
• Updated junction-to-board characterization parameter from 34.2 °C/W to 87.0 °C/W	5
• Added <i>Receiving Notification of Documentation Updates</i> section	28

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP112-Q1	SLOS887D	SLOS887E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP112-Q1>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP112AQDRLRQ1			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com